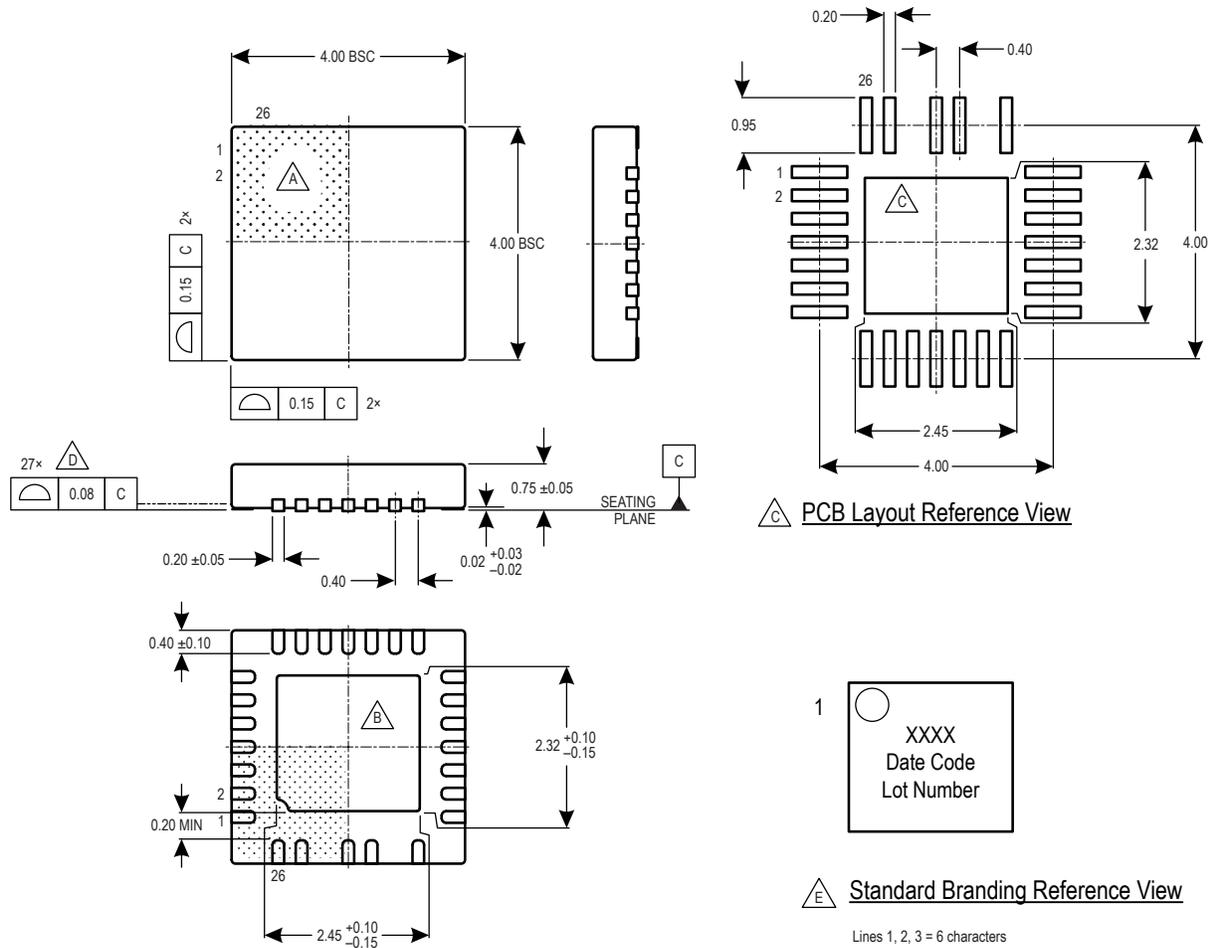


For Reference Only – Not for Tooling Use

(Reference DWG-0000222, Rev. 6)
NOT TO SCALE

All dimensions nominal unless otherwise stated – Dimensions in millimeters
Exact case and lead configuration at supplier discretion within limits shown



- A** Terminal #1 mark area
- B** Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion)
- C** Reference land pattern layout (reference IPC7351 QFN40P400X400X80-29M) all pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)
- D** Coplanarity includes exposed thermal pad and terminals
- E** Branding scale and appearance at supplier discretion.

E Standard Branding Reference View

Lines 1, 2, 3 = 6 characters

Line 1: Part Number
Line 2: 4 digit Date Code
Line 3: Characters 5, 6, 7, 8 of Assembly Lot Number

Pin 1 Dot top left
Center align

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